

SANYO Semiconductors

DATA SHEET

An ON Semiconductor Company

2SK715 — N-Channel Junction Silicon FET

AM Tuner, RF Amplifier Applications

Applications

- · AM tuner RF amp, low-noise amp
- · HF low-noise amp

Features

- · Adoption of FBET process
- · Large | yfs |
- · Small Ciss
- · Very low noise figure

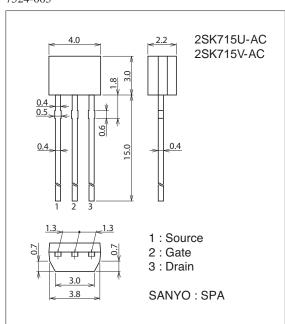
Specifications

Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Conditions	Ratings	Unit
Drain-to-Source Voltage	VDSS		15	V
Gate-to-Drain Voltage	VGDS		-15	V
Gate Current	IG		10	mA
Drain Current	ID		50	mA
Allowable Power Dissipation	PD		300	mW
Junction Temperature	Tj		125	°C
Storage Temperature	Tstg		-55 to +125	°C

Package Dimensions

unit : mm (typ) 7524-005



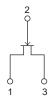
Product & Package Information

Package : SPA
JEITA, JEDEC : SC-72
Minimum Packing Quantity : 2,500 pcs./box

Marking



Electrical Connection



Electrical Characteristics at Ta=25°C

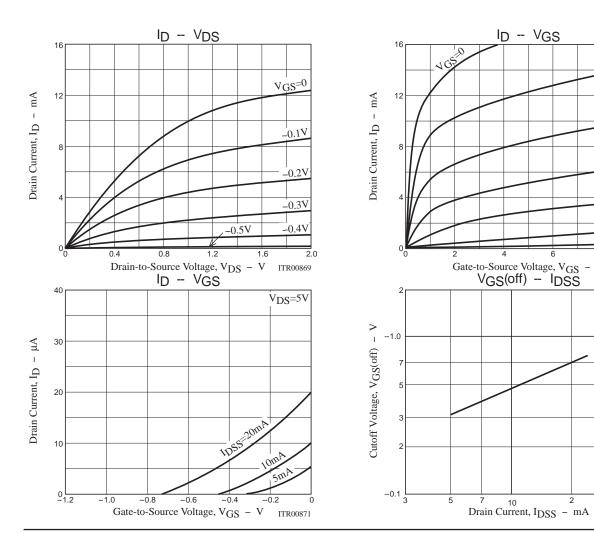
Parameter	Symbol	Conditions	Ratings			Unit
	Symbol		min	typ	max	Offic
Gate-to-Drain Breakdown Voltage	V(BR)GDS	IG=-10μA, VDS=0V	-15			V
Gate-to-Source Leakage Current	IGSS	V _{GS} =-10V, V _{DS} =0V			-1.0	nA
Zero-Gate Voltage Drain Current	IDSS*	V _{DS} =5V, V _{GS} =0V	5.0*		24.0*	mA
Cutoff Voltage	VGS(off)	V _{DS} =5V, I _D =100μA		-0.6	-1.4	V
Forward Transfer Admittance	yfs		25	50		mS
Input Capacitance	Ciss	V _{DS} =5V, V _{GS} =0V, f=1kHz		10		pF
Reverse Transfer Capacitance	Crss			3.0		pF
Noise Figure	NF	V_{DS} =5V, R_g =1k Ω , I_D =1mA, f=1kHz		1.5		dB

* : The 2SK715 is classified by IDSS as follows: (unit: mA)

Rank	Т	U	V	W
IDSS	5.0 to 8.5	7.3 to 12.0	10.0 to 17.0	14.5 to 24.0

Ordering Information

Device	Package	Shipping	memo
2SK715U-AC	SPA	2,500pcs./box	Pb Free
2SK715V-AC	SPA	2,500pcs./box	Fb Fiee



ITR00872

V1.0_

-0.2V

_0.3V

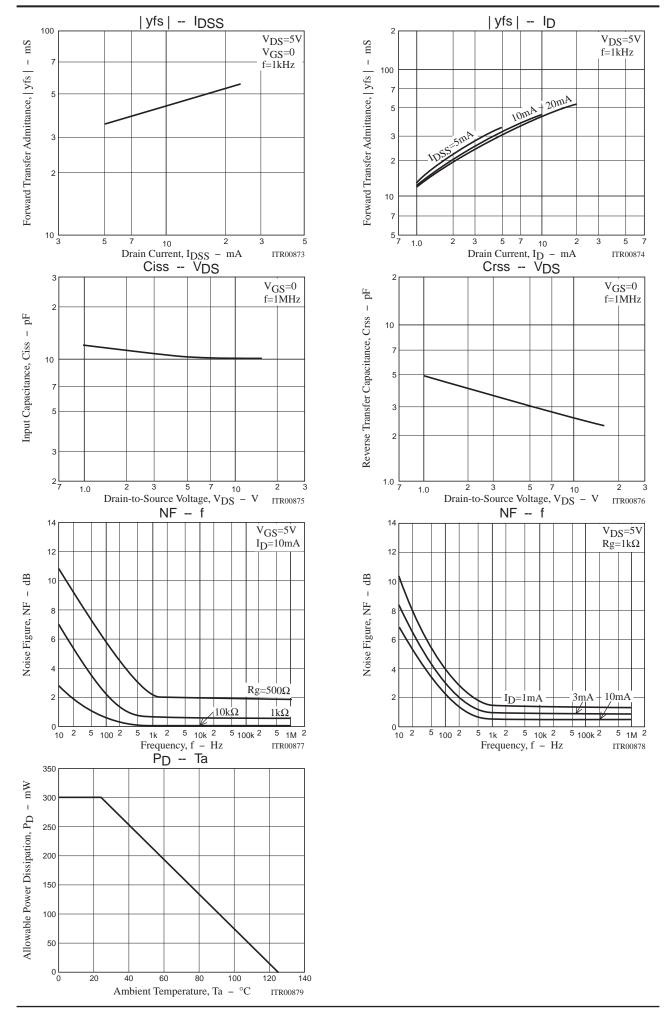
-0.4V

_0.5V

-0.6V

ITR00870

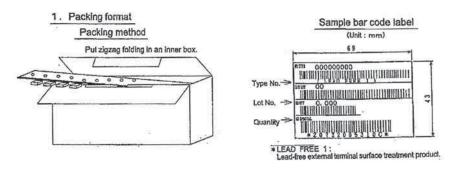
V_{DS}=5V I_D=100μA



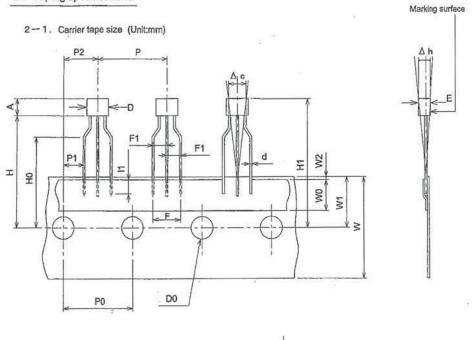
Taping Specification

2SK715U-AC, 2SK715V-AC

Storage package Package Outline name type	Package	Maximum Number of devices contained(pcs.)		Packing format		
	Inner box No.	Storage quanktiy	Outer box (C-6)	Outer box (C-8)		
	A C	C-2 Inner box Dimensions :mm(external) 330 × 45 × 145	2,500	16 inner boxes contained (40,000pcs.) Outer box Dimensions:mm(external) 5 8 5 × 3 4 5 × 2 0 0	8 inner boxes contained (20,000pcs. Outer box Dimensions:mm(external 3 4 5 × 3 0 0 × 2 0 0	
SPA A L	C-2 Inner box Dimensions xmm(external) 330 × 45 × 145	2,400	16 inner boxes contained (38,400pcs.) Outer box Dimensions:mm(external) 5 8 5 × 3 4 5 × 2 0 0	8 inner boxes contained(19,200pcs.) Outer box Dimensions:mm(internal) 3 4 5 × 3 0 0 × 2 0 0		
	AP	C — 4 Inner box Dimensions :mm(external) 330 × 45 × 285	5,000	8 Inner boxes contained (40,000pcs.) Outer box Dimensions:mm(external) 5 8 5 × 3 4 5 × 2 0 0	4 inner boxes contained(20,000pcs.) Outer box Dimensions:mm(internal) 3 4 5 × 3 0 0 × 2 0 0	
	AS	C-2 Inner box Dimensions mm(external) 330 × 45 × 145	1,200	16 inner boxes contained(19,200 pcs.) Outer box Dimensions:mm(external) 5 8 5 × 3 4 5 × 2 0 0	8 inner boxes contained(9,600 pcs.) Outer box Dimensions:mm(intenal) 3 4 5 × 3 0 0 × 2 0 0	



2. Taping specifications



2-2. Taping size standard

Item	Symbol	Standard	Tolerance
Tape width	w	18.0	+1.0 -0.5
Adhesive tape	wo	6.0	±1.0
Displacement of perforations	W1	9.0	+0.75
Work piece bottom surface position	Н	19.8	+1.0 -0.3
Lead wire clinch height	HO	16.0	+0.5

H1

DO

t

Δο

Unit:mm

22.8

 $\phi 4.0$

0.6

±1.5

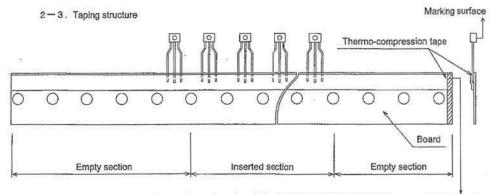
±0.2

±0.2

±1.0

Item	Symbol	Standard	Tolerance	Item
	D	4.0	±0.2	Tape width
Work piece outside diameter	E	2.2	±0.2	Adhesive tape
Work piece height	Α	3.0	±0.2	Displacement of perforations
Lead wire diameter	d	0.4×0.4 t	±0.1	Work piece bottom surface position
Bonded lead wire	11	2.5MIN		Lead wire clinch height
Pitch between products	Р	12.7	±1.0	Work piece upper limit position
Pitch between perforations	P0	12.7	±0.2	Perforations diameter
Total pitch for 21 perforations	P0×20	254.0	±1.0	Tape thickness (total thickness)
Distance between lead wire	F	5.0	+0.8	Product inclination
Lead wire pitch distance	F1	2.5	+0.4	
Product inclination	Δh	0	±2.0	
Displacement of perfections	P1	3.85	±0.3	To be measured at a position below the clinch
Displacement of perforations	P2	6.35	±0.3	1000000 100000 100000 100000 100000 100000 100000 100000 1000000
Displacement of tape	W2	0.5MAX	,	Not to be displaced to the outside of the board

position o ard

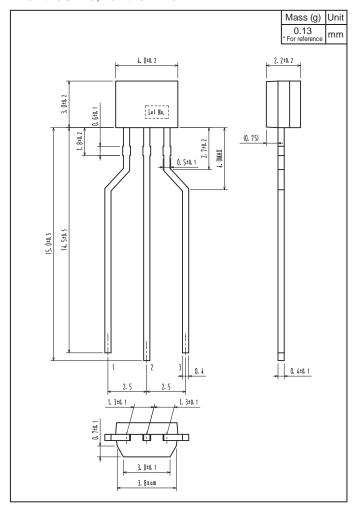


- · Provide an empty section for about three to five pieces in leading and end portions of the tape.
- Marked in red

· Provide marking in red to the E-side end of the board.

Outline Drawing

2SK715U-AC, 2SK715V-AC



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